

GLASS PASSIVATED FAST RECOVERY BRIDGE RECTIFIERS

Features

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°C /10 seconds at 5
- ◆ lbs., (2.3kg) tension Small size, simple installation
- ◆ Leads solderable per MIL-STD-202, Method 208
- ◆ High surge current capability
- ◆ Glass passivated chip junction
- ◆ Green compound(halogen&Sb2O3 free)

Mechanical Data

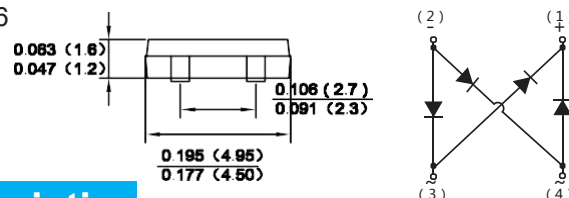
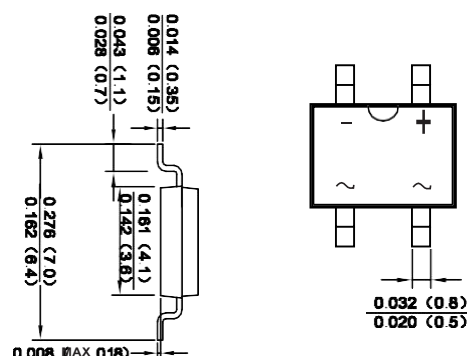
Case : JEDEC MBF Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0026 ounce, 0.075 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Dimensions in inches and (millimeters)

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	RCD RMB2F	RCD RMB4F	RCD RMB6F	RCD RMB8F	RCD RMB10F	UNITS
Marking Code							
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	I _{F(AV)}	0.5 0.8					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30					A
Maximum instantaneous forward voltage drop per leg at 0.4A	V _F	1.3					V
Maximum DC reverse current T _A =25°C T _A at rated DC blocking voltage =100°C	I _R	5 0.5					uA mA
Maximum reverse recovery time	t _{rr}	150		250	200		ns
Typical thermal resistance Note3	Rθ _{JL} Rθ _{JA}	30 88					°C/W
Operating temperature range Note4	T _J	-55 to +150-					°C
storage temperature range	T _{STG}	55 to +150					°C

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.

2.On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.

3.Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

4.Reverse recovery condition $I_F=0.5A$, $I_R=1.0A$, $I_{rr}=0.25A$.

FIG.1 FORWARD DERATING CURVE

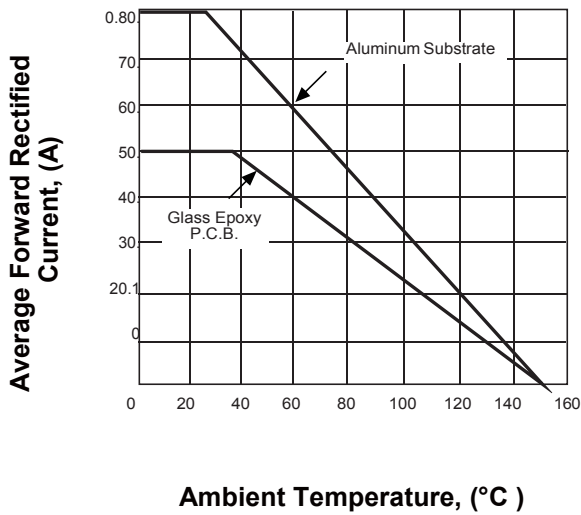


FIG.2 PEAK FORWARD SURGE CURRENT

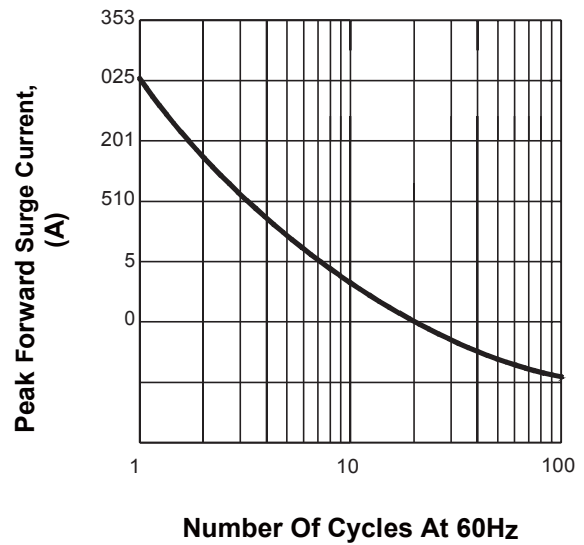


FIG.3 TYPICAL FORWARD CHARACTERISTICS

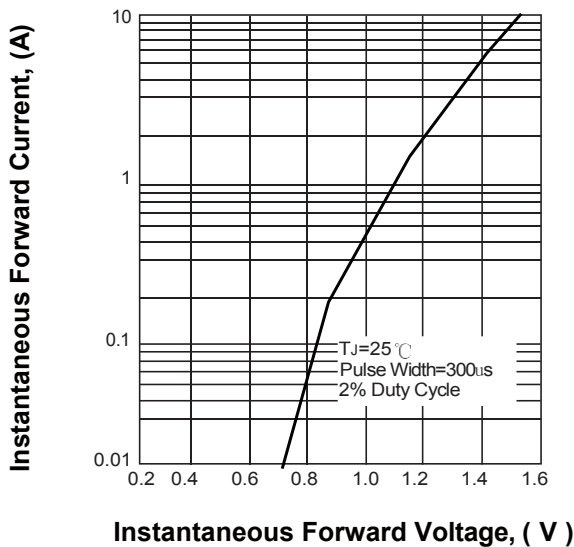
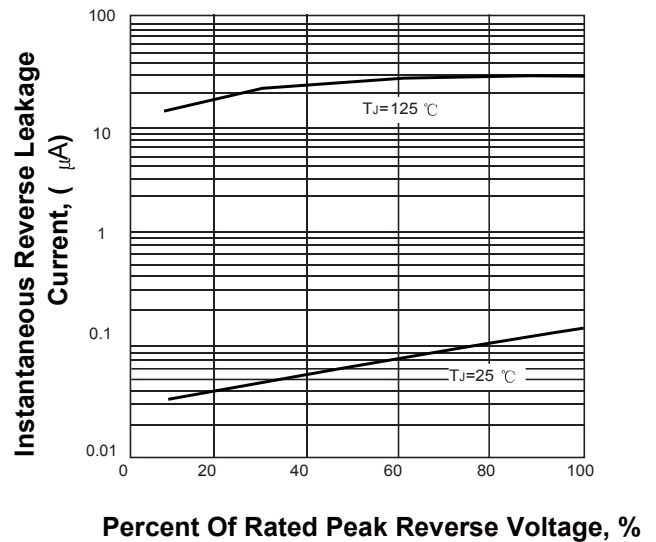
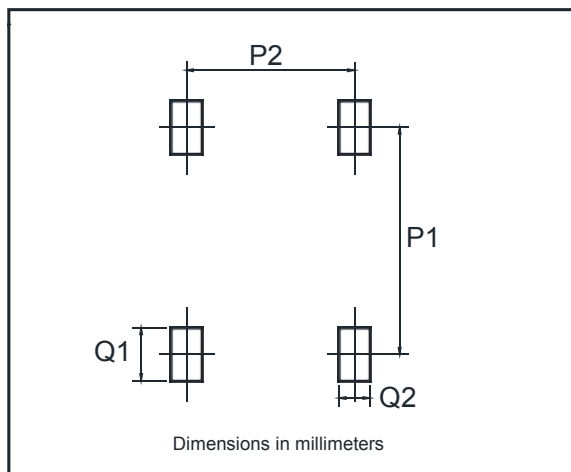


FIG.4 TYPICAL REVERSE CHARACTERISTICS





Dim	Min
P1	6.00
P2	2.40
Q1	1.84
Q2	1.20